

SPECIFICATION

Page 1, Total 28 Pages



OLED SPECIFICATION

Model No:

RET025664BWPP3N00000

CUSTOMER:

APPROVED BY

PCB VERSION

DATE

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY	
Release DATE:				



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2014/06/23		First release
А	2014/12/03		Modify Electrical
			Characteristics&Brightness
В	2015/12/22		Modify Life Time
С	2016/06/01		Modify Static electricity test



Contents

- **1.General Specification**
- 2.Module Classification Information
- **3.Interface Pin Function**
- 4.Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
- **6.**Electrical Characteristics
- 7. Optical Characteristics
- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

- Module dimension: 88.0 × 27.8 × 2.05 mm
- Active area: 76.778×19.178 mm
- Dot Matrix : 256 x 64
- Dot Size: 0.278×0.278 mm
- Dot Pitch: 0.3×0.3mm
- Display Mode: Passive Matrix
- Duty: 1/64
- Display Color: White
- IC: SSD1322



2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13
R	Е	Т	025664	В	W	Р	Р	3	Ν	0	0	000

Item	Description						
1	R : Raystar Optron	R : Raystar Optronics Inc.					
2	E : OLED						
3	Display Type: C→C	Character Type, G→Graphic Ty	rpe,T→TAB Type ,X→COG Type				
4	Dot Matrix : 256*	64					
5	Serials code						
		A : Amber	R : RED				
6	Emitting Color	B : Blue	Y : Yellow				
0	6 Emitting Color	G : Green	W : White				
		S : Sky Blue					
7	Polarizer	P: With Polarizer; N: Withou	t Polarizer				
8	Display Mode	P: Passive Matrix ; A: Active	P: Passive Matrix ; A: Active Matrix				
9	Driver Voltage	3: 3.0 V; 5: 5.0V					
10	Touch Panel	N : Without touch panel; T: W	/ith touch panel				
		S : Resistive touch panel					
11	Products type	0:Standard type 1: Sunlight Readable type 2:Transparent OLED (TOLED 3:Flexible OLED 4:OLED for Lighting					
12	Product grades	 0 : Standard(A-level) 2: B-level 3: C-level 1: high class(AA-level) Y: Consumer product 					
13	Serial No.	Application serial number(000	0~ZZZ)				



3.Interface Pin Function

Pin Number	Symbol	I/O	Function
Power Sup	oply		
26	VCI	P	Power Supply for Operation This is a voltage supply pin. It must be connected to external source & always be equal to or higher than VDD & VDDIO.
25	VDD	Ρ	Power Supply for Core Logic Circuit This is a voltage supply pin. It can be supplied externally (within the range of 2.4~2.6V) or regulated internally from VCI. A capacitor should be connected between this pin & VSS under all circumstances.
24	VDDIO	Ρ	Power Supply for I/O Pin This pin is a power supply pin of I/O buffer. It should be connected to VDD or external source. All I/O signal should have VIH reference to VDDIO. When I/O signal pins (BS0~BS1, D0~D7, control signals) pull high, they should be connected to VDDIO.
2	VSS	Р	Ground of Logic Circuit This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.
3,29	VCC	P	Power Supply for OLED Panel These are the most positive voltage supply pin of the chip. They must be connected to external source.
5,28	VLSS	Р	<i>Ground of Analog Circuit</i> These are the analog ground pins. They should be connected to VSS externally.
Driver			
22	IREF		<i>Current Reference for Brightness Adjustment</i> This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current lower than 10uA.
4	VCOMH	Р	Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A tantalum capacitor should be connected between this pin and VSS.
27	VSL	Ρ	Voltage Output Low Level for SEG Signal This is segment voltage reference pin. When external VSL is not used, this pin should be left open. When external VSL is used, this pin should connect with resistor and diode to ground.



Testing Pad	S		
21	FR	0	Frame Frequency Triggering Signal
			This pin will send out a signal that could be used to identify the
			driver status. Nothing should be connected to this pin. It should
			be left open individually.
16	BS0	I	Communicating Protocol Select
17	BS1		These pins are MCU interface selection input. See the following
			table:
			BS0 BS1
			3-wire SPI 1 0
			4-wire SPI 0 0
			8-bit 68XX Parallel 1 1
			8-bit 80XX Parallel 0 1
20	RES#	1	Power Reset for Controller and Driver
			This pin is reset signal input. When the pin is low, initialization
			of the chip is executed.
19	CS#	Ι	Chip Select
			This pin is the chip select input. The chip is enabled for MCU
			communication only when CS# is pulled low.
18	D/C#		Data/Command Control
			This pin is Data/Command control pin. When the pin is pulled
			high, the input at D7~D0 is treated as display data.
			When the pin is pulled low, the input at D7~D0 will be
			transferred to the command register. For detail relationship to
			MCU interface signals, please refer to the
	E / DD #		Timing Characteristics Diagrams.
14	E/RD#		Read/Write Enable or Read
			This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the
			Enable (E) signal. Read/write operation is initiated when this
			pin is pulled high and the CS# is pulled low.
			When connecting to an 80XX-microprocessor, this pin receives
~			the Read (RD#) signal. Data read operation is initiated when
			this pin is pulled low and CS# is pulled low.
7			When serial mode is selected, this pin must be connected to
			VSS.
15	R/W#	Ι	Read/Write Select or Write
			This pin is MCU interface input. When interfacing to a
× ·			68XX-series microprocessor, this pin will be used as
			Read/Write (R/W#) selection input. Pull this pin to "High" for
			read mode and pull it to "Low" for write mode.
			When 80XX interface mode is selected, this pin will be the
			Write (WR#) input. Data write operation is initiated when this
			pin is pulled low and the CS# is pulled low. When serial mode is selected, this pin must be connected to
	1	1	I when serial mode is selected this hin must be connected to

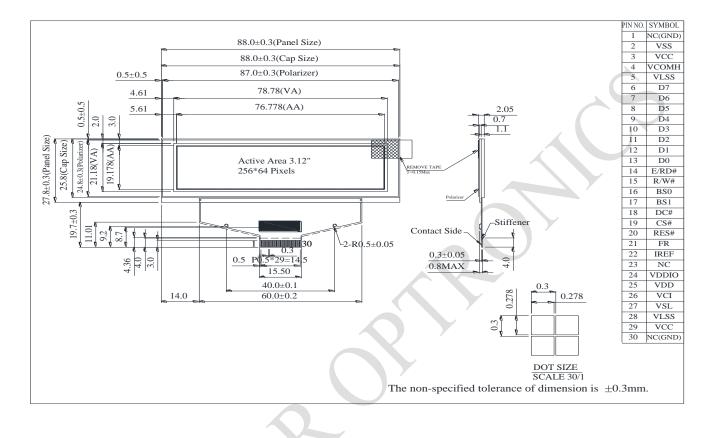
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			VSS.
6~13	D7~D0	I/O	Host Data Input/Output Bus These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. Unused pins must be connected to VSS except for D2 in serial mode.
Reserve			
23	N.C.	-	Reserved Pin The N.C. pin between function pins are reserved for compatible and flexible design.
1,30	N.C. (GND)	-	Reserved Pin (Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground.

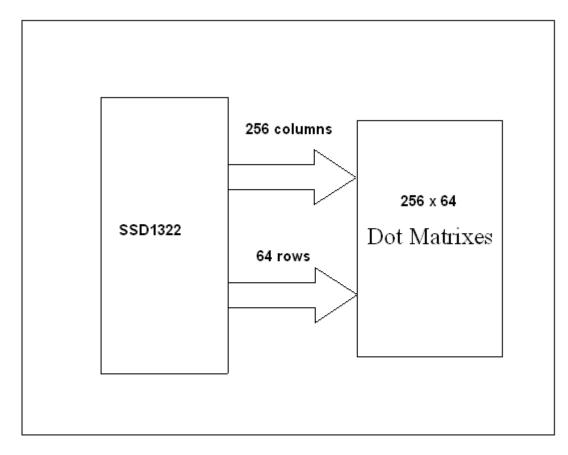


4.Counter Drawing & Block Diagram





FUNCTION BLOCK DIAGRAM



*For more information, please refer to Application Note provided by Raystar Optronics.



Page 11, Total 28 Pages



5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Operation	VCI	-0.3	4	V	1, 2
Supply Voltage for Logic	VDD	-0.5	2.75	V	1, 2
Supply Voltage for I/O Pins	VDDIO	-0.5	VCI	V	1, 2
Supply Voltage for Display	VCC	-0.5	20	V	1, 2
Operating Temperature	TOP	-40	80	°C	-
Storage Temperature	TSTG	-40	80	O°	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



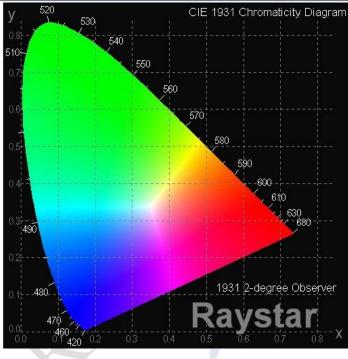
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Мах	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	—	10	12	15	V
High Level Input	VIH	—	0.8×VDD		VDD	V
Low Level Input	VIL	—	0	- /	0.2×VDD	V
High Level Output	VOH	—	0.9×VDD	×	VDD	V
Low Level Output	VOL	—	0	-	0.1×VDD	V
50% Check Board operatir Current	ng	VCC =12V	22	24	27	mA



7.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ		160	_	-	deg
view / angle	(H)φ		160	_		deg
Contrast Ratio	CR	Dark	2000:1	-	-	
Response Time	T rise	_	_	10		μs
	T fall	_	-	10		μs
Display with 50% check E		60	80	—	cd/m2	
CIEx(White)		(CIE1931)	0.26	0.28	0.30	—
CIEy(White)	(CIE1931)	0.30	0.32	0.34	—	





8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25℃ / Initial 50% check board brightness Typical Value	20,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Environmenta	l Test		
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 240hrs	- (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40℃ 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40℃ 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C ,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40℃/80℃ 100 cycles	
Mechanical Tes	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	50
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	

*** Supply voltage for OLED system =Operating voltage at $25^\circ\!\mathrm{C}$



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



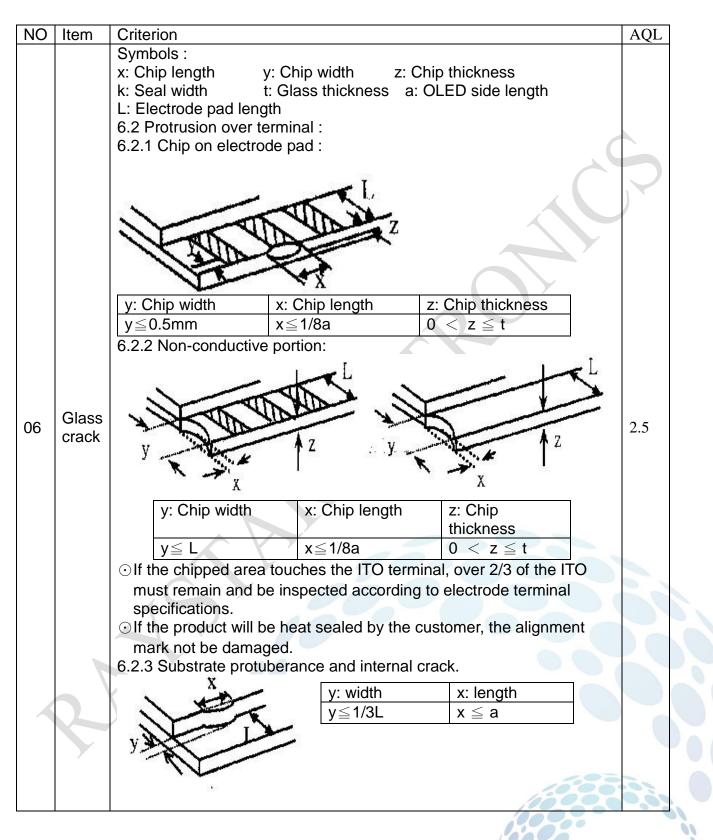
10.Inspection specification

NO	Item	Criterion					AQL	
01	Electrical	1.1 Missing vertical, horizontal segment, segment contrast			/.QL			
	Testing	defect.						
	J	1.2 Missing character , dot or icon.						
		1.3 Display malfunction.				(
		1.4 No function	or no displ	ay.			0.65	
		1.5 Current consumption exceeds product specifications.			pecifications.	0.05		
		1.6 OLED viewing angle defect.						
		1.7 Mixed produ						
		1.8 Contrast def	ect.					
02	Black or	2.1 White and b	lack snots	00.0	$ _{1} = $	mm no more than		
02	2 Black or 2.1 White and black spots on display ≤ 0.25 mm, no more white three white or black spots present.			nin, no more than				
	spots on	2.2 Densely spaced: No more than two spots or lines within						
	OLED	3mm.					2.5	
	(display							
	only)					/		
03	OLED	3.1 Round type						
	black	following drawin	g		SIZE	Acceptable Q		
	spots,	Φ=(x + y) / 2	(★ < 0.40	TY		
	white	X III			Ф≦0.10	Accept no		
	spots, contamina		<u> </u>		0.10<	dense 2	2.5	
	tion	· • -	Y		0.10< Φ≦0.20	2	2.0	
	(non-displ	1			Ψ <u>≧</u> 0.20 0.20<	1		
	ay)							
			Y		Φ≦0.25	0		
					0.25<Φ	0		
		3.2 Line type : (/		-	•	Acceptable O TV		
	A	×	Length	_	dth	Acceptable Q TY		
		\sim $4 - \frac{1}{2}$			≤ 0.02	Accept no dense	2.5	
		→ L +	L≦3.0		$2 < W \le 0.03$	2	2.0	
			L≦2.5	_	03 <w≦0.05< td=""><td></td><td></td></w≦0.05<>			
				0.0	95 <w< td=""><td>As round type</td><td></td></w<>	As round type		
04	Polarizer							
	bubbles If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.				Acceptable Q TY			
				≦0.20	Accept no dense			
					0.2	$20 < \Phi \le 0.50$	3	2.5
			0.5	50<Φ≦1.00	2	0.0		
			1.0	Φ>00	0			
				То	tal Q TY	3 00 0		
	•						·I	



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
			t: Glass thickness a	Chip thickness :: OLED side length	
		6.1 General glass ch 6.1.1 Chip on panel s	ip : surface and crack bet	ween panels:	P
06		z: Chip thickness	y: Chip width	x: Chip length	
	Chipped glass	Z≦1/2t	Not over viewing area	x≦1/8a	2.5
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a	
⊙ If there are 2 or more 6.1.2 Corner crack:			y		10
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \le 1/2t$	Not over viewing area	x.emplengin x≦1/8a	P
		1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
		\odot If there are 2 or mo	ore chips, x is the tota	al length of each chip.	







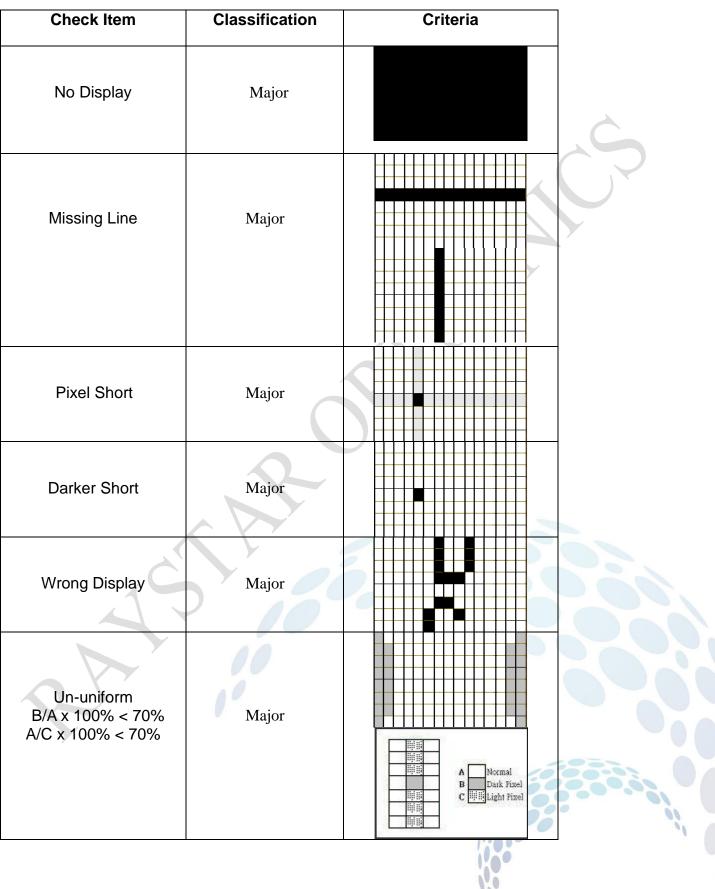
NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	 2.5 2.5 0.65 2.5 0.65 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



Item	Criterion	AQL
General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
	12.2 No cracks on interface pin (OLB) of TCP.	0.65
	12.3 No contamination, solder residue or solder balls on	2.5
	product.	2.5
		2.5
	interface pin must be present or look as if it cause the interface pin to sever.	2.5
	12.6 The residual rosin or tin oil of soldering (component or	2.5
	chip component) is not burned into brown or black color.	0.65
		0.65
		0.65
	12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
	product specification sheet.	
	General	General appearance12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP.

Page 22, Total 28 Pages







11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)

(11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

11.1 Handling Precautions

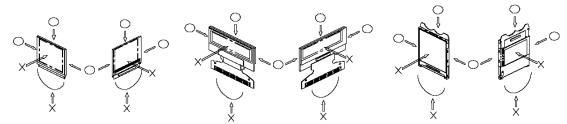
- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

* Water

- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.





- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.(We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.



11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.



		Page: 1			
Module Sample Estimate Feedback Sheet					
Module Number :	Module Number :				
1 <u> Panel Specification</u> :					
1. Panel Type:	Pass	□NG ,			
2. Numbers of Pixel :	Pass	□NG ,			
3. View Area :	Pass	□NG ,			
4. Active Area :	Pass	□NG ,			
5.Emitting Color :	Pass	□NG ,			
6.Uniformity:	□Pass	□NG ,			
7.Operating	Pass	□NG ,			
Temperature :		Y			
8.Storage Temperature :	Pass	□NG ,			
9.Others :	÷				
2 · Mechanical Specificati	on :				
1. PCB Size :	□Pass	□NG ,			
2.Frame Size :	□Pass	□NG ,			
3.Materal of Frame :	□Pass	□NG ,			
4.Connector Position :	□Pass	□NG ,			
5.Fix Hole Position :	□Pass	□NG ,			
6. Thickness of PCB :	□Pass	□NG ,			
7. Height of Frame to	□Pass	□NG ,			
PCB :	Г <mark>С</mark> У				
8.Height of Module :	□Pass	□NG ,			
9.Others :	□Pass	□NG ,			
3 · <u>Relative Hole Size</u> :					
1.Pitch of Connector :	□Pass	□NG ,			
2.Hole size of	□Pass	□NG ,			
Connector :					
3.Mounting Hole size :	□Pass	□NG ,			
4.Mounting Hole Type :	□Pass	□NG ,			
5.Others :	□Pass	□NG ,			

>> Go to page 2 <<



Page: 2

Module Number :				
4 · Electronic Characteristics of Module				
1.Input Voltage :	□Pass	□NG ,		
2.Supply Current :	□Pass	□NG ,		
3.Driving Voltage for OLED :	□Pass	□NG ,		
4.Contrast for OLED :	□Pass	□NG ,		
5.Negative Voltage Output :	□Pass	□NG ,		
6.Interface Function :	□Pass	□NG ,		
7.ESD test :	□Pass	□NG ,		
8.Others :	□Pass	□NG ,		

5 \ <u>Summary</u> :

Sales signature : _____ Customer Signature : ____

Date : / /